

Title (en)

ELECTRONIC PACKAGE SEALED WITH A DISPENSABLE ADHESIVE.

Title (de)

ELEKTRONIKGEHAUSE, DAS MIT EINEM VERTEILBAREN KLEBSTOFF VERSIGELT WIRD.

Title (fr)

COMPOSANT ELECTRONIQUE SCELLE A L'AIDE D'UN ADHESIF EN DISTRIBUTEUR.

Publication

EP 0673547 A4 19960313 (EN)

Application

EP 94901644 A 19931122

Priority

- US 9311337 W 19931122
- US 98786792 A 19921209

Abstract (en)

[origin: WO9414193A1] There is provided a method for the assembly of an electronic package (48) utilizing liquid adhesives (30, 46). A first liquid adhesive (30) is dispensed on a base (12) and a leadframe (16) is supported by the liquid adhesive (30). A second liquid adhesive (46) is dispensed, overlying the first liquid adhesive (30) and the leadframe (16), and supports a cover (14). The entire assembly is then thermally cured. Means to control the flow of the liquid adhesives (52) and to reduce the mutual inductance between leads (72) are also provided.

IPC 1-7

H01L 23/48; **H01L 23/02**; **H01L 23/12**; **H01L 29/44**; **H01L 29/52**; **H01L 29/60**; **H01L 21/60**

IPC 8 full level

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CPC (source: EP)

H01L 21/50 (2013.01); **H01L 23/10** (2013.01); **H01L 24/49** (2013.01); **H01L 2224/49171** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/01039** (2013.01); **H01L 2924/01078** (2013.01); **H01L 2924/01079** (2013.01); **H01L 2924/10253** (2013.01); **H01L 2924/14** (2013.01); **H01L 2924/163** (2013.01); **H01L 2924/30107** (2013.01)

Citation (search report)

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- See references of WO 9414193A1

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